Vishay Semiconductors

High Speed Infrared Emitting Diodes, 850 nm, GaAlAs, DH



www.vishay.com

DESCRIPTION

VSMG2000X01 series are infrared, 850 nm emitting diodes in GaAlAs (DH) technology with high radiant power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

FEATURES

- · Package type: surface mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- AEC-Q101 qualified
- Peak wavelength: $\lambda_p = 850 \text{ nm}$
- High reliability
- High radiant power
- · High radiant intensity
- Angle of half intensity: $\phi = \pm 12^{\circ}$
- Low forward voltage
- · Suitable for high pulse current operation
- Terminal configurations: gullwing or reserve gullwing
- Package matches with detector VEMD2000X01 series
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- IrDA compatible data transmission
- IR-illumination (CCTV)
- Miniature light barrier
- Photointerrupters
- Optical switch
- Shaft encoders
- IR emitter source for proximity applications

PRODUCT SUMMARY				
COMPONENT	I _e (mW/sr)	φ (deg)	λ _p (nm)	t _r (ns)
VSMG2000X01	40	± 12	850	20
VSMG2020X01	40	± 12	850	20

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMG2000X01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing
VSMG2020X01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing

Note

• MOQ: minimum order quantity

AUTOMOTIVE GRADE



(5-2008)



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ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25 \text{ °C}$, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	5	V
Forward current		I _F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \ \mu s$	I _{FM}	200	mA
Surge forward current	t _p = 100 μs	I _{FSM}	1	А
Power dissipation		Pv	170	mW
Junction temperature		Tj	100	°C
Operating temperature range		T _{amb}	- 40 to + 85	°C
Storage temperature range		T _{stg}	- 40 to + 100	°C
Soldering temperature	Acc. figure 9, J-STD-020	T _{sd}	260	°C
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	R _{thJA}	250	K/W

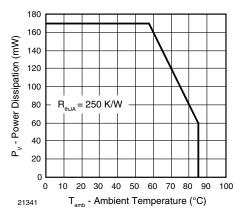


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

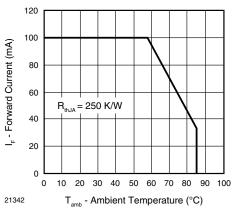


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 100 mA, t _p = 20 ms	V _F	1.25	1.45	1.7	V
	I _F = 1 A, t _p = 100 μs	V _F		2.3		V
Temperature coefficient of V_F	I _F = 1 mA	TK _{VF}		- 1.8		mV/K
	I _F = 100 mA	TK _{VF}		- 1.1		mV/K
Reverse current	V _R = 5 V	I _R			10	μA
Junction capacitance	$V_{R} = 0 V, f = 1 MHz, E = 0 mW/cm^{2}$	CJ		125		pF
Radiant intensity	I _F = 100 mA, t _p = 20 ms	l _e	20	40	60	mW/sr
	I _F = 1 A, t _p = 100 μs	l _e		350		mW/sr
Radiant power	I _F = 100 mA, t _p = 20 ms	φ _e		40		mW
Temperature coefficient of ϕ_{e}	I _F = 100 mA	TKφ _e		- 0.35		%/K
Angle of half intensity		φ		± 12		deg
Peak wavelength	I _F = 30 mA	λ _p	830	850	870	nm
Spectral bandwidth	I _F = 30 mA	Δλ		35		nm
Temperature coefficient of λ_{p}	I _F = 30 mA	ΤΚλρ		0.25		nm/K
Rise time	I _F = 100 mA, 20 % to 80 %	t _r		20		ns
Fall time	I _F = 100 mA, 20 % to 80 %	t _f		20		ns
Cut-off frequency	$I_{DC} = 70 \text{ mA}, I_{AC} = 30 \text{ mA pp}$	f _c		23		MHz
Virtual source diameter		d		1.5		mm

Document Number: 85194

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BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

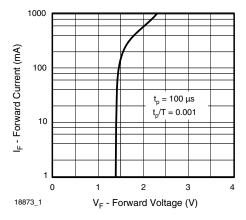


Fig. 3 - Forward Current vs. Forward Voltage

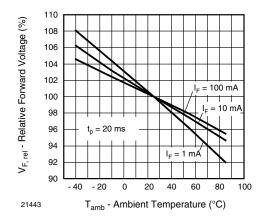


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

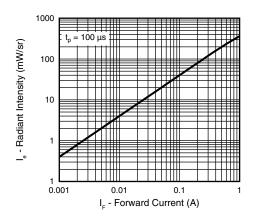


Fig. 5 - Radiant Intensity vs. Forward Current

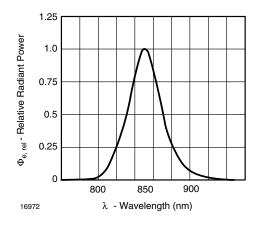


Fig. 6 - Relative Radiant Power vs. Wavelength

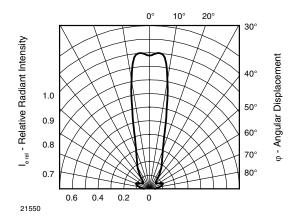


Fig. 7 - Relative Radiant Intensity vs. Angular Displacement

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255

-240 °C

-217 °C

SOLDER PROFILE

Temperature (°C)

300

250

200

150

100

50

0

19841

0

50

VSMG2000X01, VSMG2020X01

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DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: T_{amb} < 30 °C, RH < 60 % Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

PACKAGE DIMENSIONS in millimeters: VSMG2000

nax. ramp up 3 °C/s max. ramp down 6 °C/s

150

Time (s)

Fig. 8 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

max. 120

100

<u>max.</u> 260 °C

max. 30 s

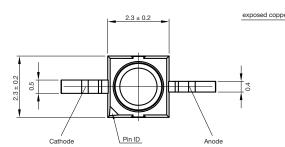
max. 100 s

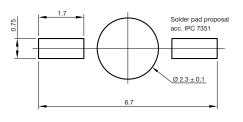
200

250

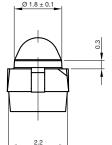
300

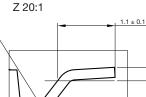
245





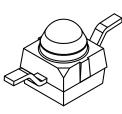
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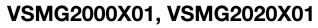
technical drawings according to DIN specifications 0.254

Not indicated tolerances $\pm \ 0.1$



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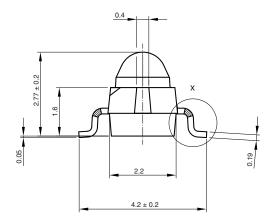
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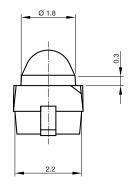




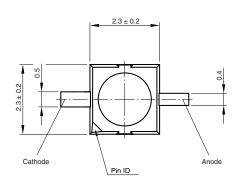
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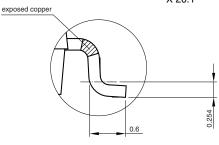
PACKAGE DIMENSIONS in millimeters: VSMG2020





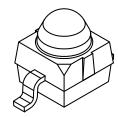
X 20:1







Not indicated tolerances ± 0.1



	Solder pad proposal acc. IPC 7351
-	
	2.45
	5.15

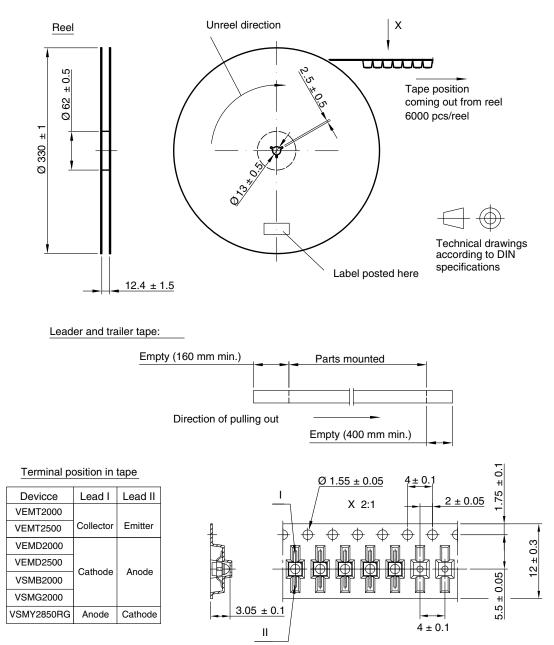
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TAPING AND REEL DIMENSIONS in millimeters: VSMG2000



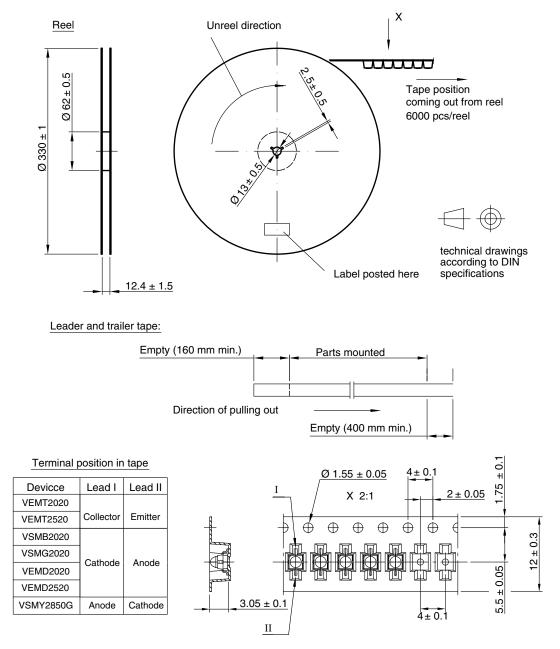
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TAPING AND REEL DIMENSIONS in millimeters: VSMG2020



Drawing-No.: 9.800-5091.01-4 Issue: 3; 18.03.10 21571



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